

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
Szu-Chia Huang	08/31/2011
Jhieh Jie Shao	08/31/2011
Tang-Hsuan Chung	08/31/2011
Huan Chi Tseng	08/31/2011
<b>RECEIVING PARTY DATA</b>	
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Road 6
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
Property Type	Number
Application Number:	13225816
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NAME OF SUBMITTER:	Eric Q. Li
Total Attachments: 2 source=1887_Assignment#page1.tif source=1887_Assignment#page2.tif	

OP \$40.00 13225816

**ASSIGNMENT**

WHEREAS, we,

- (1) Szu-Chia Huang of 7F, No. 10, Lane 476, Sec. 1, Guangfu Road  
Hsinchu City 300, Taiwan, R.O.C.
- (2) Jhih Jie Shao of No. 3, Lane 65, Tianxiang Street  
Toufen Township, Miaoli County 351, Taiwan, R.O.C.
- (3) Tang-Hsuan Chung of 5F-2, No. 4, Lane 129, Heping 1st Road, Lingya District  
Kaohsiung City 802, Taiwan, R.O.C.
- (4) Huan Chi Tseng of 4F, No. 28, Alley 15, Lane 582, Sida Road  
Hsinchu City 300, Taiwan R.O.C.

have invented certain improvements in

**METHOD AND APPARATUS FOR TESTING A SEMICONDUCTOR DEVICE**

for which we have executed an application for Letters Patent of the United States of America, filed on 09-06-2011 and assigned application number 13/225,816; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional,

continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Szu-Chia Huang

Residence Address: 7F, No. 10, Lane 476, Sec. 1, Guangfu Road  
Hsinchu City 300, Taiwan, R.O.C.

Dated: ✓ Szu-Chia Huang

✓ 8/31, 2011  
Inventor Signature

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Inventor Name: Jhih Jie Shao

Residence Address: No. 3, Lane 65, Tianxiang Street  
Toufen Township, Miaoli County 351, Taiwan, R.O.C.

Dated: ✓ Jhih Jie Shao

✓ 8/31, 2011  
Inventor Signature

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Inventor Name: Tang-Hsuan Chung

Residence Address: 5F-2, No. 4, Lane 129, Heping 1st Road, Lingya District  
Kaohsiung City 802, Taiwan, R.O.C.

Dated: ✓ Tang-Hsuan Chung

✓ 8/31, 2011.  
Inventor Signature

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Inventor Name: Huan Chi Tseng

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Dated: ✓ Huanchi Tseng 8/31'2011

✓ Huanchi Tseng  
Inventor Signature